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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	24KB (12K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4455t-i-ml

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.0 MEMORY ORGANIZATION

There are three types of memory in PIC18 enhanced microcontroller devices:

- Program Memory
- Data RAM
- Data EEPROM

As Harvard architecture devices, the data and program memories use separate busses; this allows for concurrent access of the two memory spaces. The data EEPROM, for practical purposes, can be regarded as a peripheral device, since it is addressed and accessed through a set of control registers.

Additional detailed information on the operation of the Flash program memory is provided in **Section 6.0 "Flash Program Memory"**. Data EEPROM is discussed separately in **Section 7.0 "Data EEPROM Memory"**.

5.1 Program Memory Organization

PIC18 microcontrollers implement a 21-bit program counter which is capable of addressing a 2-Mbyte program memory space. Accessing a location between the upper boundary of the physically implemented memory and the 2-Mbyte address will return all '0's (a NOP instruction).

The PIC18F2455 and PIC18F4455 each have 24 Kbytes of Flash memory and can store up to 12,288 single-word instructions. The PIC18F2550 and PIC18F4550 each have 32 Kbytes of Flash memory and can store up to 16,384 single-word instructions.

PIC18 devices have two interrupt vectors. The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The program memory maps for PIC18FX455 and PIC18FX550 devices are shown in Figure 5-1.



FIGURE 5-1: PROGRAM MEMORY MAP AND STACK

9.4 PIE Registers

The PIE registers contain the individual enable bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are two Peripheral Interrupt Enable registers (PIE1 and PIE2). When IPEN = 0, the PEIE bit must be set to enable any of these peripheral interrupts.

REGISTER 9-6: PIE1: PERIPHERAL INTERRUPT ENABLE REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
SPPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE		
bit 7							bit 0		
Legend:									
R = Readable bit W = Writable bit				U = Unimplemented bit, read as '0'					
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cleared		x = Bit is unknown			
bit 7	SPPIE: Stream	ming Parallel P	ort Read/Write	e Interrupt Ena	able bit ⁽¹⁾				
	1 = Enables the SPP read/write interrupt								
bit 6	ADIE: A/D Converter Interrupt Enable bit								

	1 = Enables the A/D interrupt
	0 = Disables the A/D interrupt
bit 5	RCIE: EUSART Receive Interrupt Enable bit
	1 = Enables the EUSART receive interrupt0 = Disables the EUSART receive interrupt
bit 4	TXIE: EUSART Transmit Interrupt Enable bit
	1 = Enables the EUSART transmit interrupt0 = Disables the EUSART transmit interrupt
bit 3	SSPIE: Master Synchronous Serial Port Interrupt Enable bit
	1 = Enables the MSSP interrupt
	0 = Disables the MSSP interrupt
bit 2	CCP1IE: CCP1 Interrupt Enable bit
	1 = Enables the CCP1 interrupt
	0 = Disables the CCP1 interrupt
bit 1	TMR2IE: TMR2 to PR2 Match Interrupt Enable bit
	1 = Enables the TMR2 to PR2 match interrupt
	0 = Disables the TMR2 to PR2 match interrupt
bit 0	TMR1IE: TMR1 Overflow Interrupt Enable bit
	1 = Enables the TMR1 overflow interrupt
	0 = Disables the TMR1 overflow interrupt

Note 1: This bit is reserved on 28-pin devices; always maintain this bit clear.

Pin	Function	Setting	1/0	І/О Туре	Description
RD0/SPP0	RD0	0	OUT	DIG	LATD<0> data output.
		1	IN	ST	PORTD<0> data input.
	SPP0	1	OUT	DIG	SPP<0> output data; takes priority over port data.
		1	IN	TTL	SPP<0> input data.
RD1/SPP1	RD1	0	OUT	DIG	LATD<1> data output.
		1	IN	ST	PORTD<1> data input.
	SPP1	1	OUT	DIG	SPP<1> output data; takes priority over port data.
		1	IN	TTL	SPP<1> input data.
RD2/SPP2	RD2	0	OUT	DIG	LATD<2> data output.
		1	IN	ST	PORTD<2> data input.
	SPP2	1	OUT	DIG	SPP<2> output data; takes priority over port data.
		1	IN	TTL	SPP<2> input data.
RD3/SPP3	RD3	0	OUT	DIG	LATD<3> data output.
		1	IN	ST	PORTD<3> data input.
	SPP3	1	OUT	DIG	SPP<3> output data; takes priority over port data.
		1	IN	TTL	SPP<3> input data.
RD4/SPP4	RD4	0	OUT	DIG	LATD<4> data output.
		1	IN	ST	PORTD<4> data input.
	SPP4	1	OUT	DIG	SPP<4> output data; takes priority over port data.
		1	IN	TTL	SPP<4> input data.
RD5/SPP5/P1B	RD5	0	OUT	DIG	LATD<5> data output
		1	IN	ST	PORTD<5> data input
	SPP5	1	OUT	DIG	SPP<5> output data; takes priority over port data.
		1	IN	TTL	SPP<5> input data.
	P1B	0	OUT	DIG	ECCP1 Enhanced PWM output, Channel B; takes priority over port and SPP data. ⁽¹⁾
RD6/SPP6/P1C	RD6	0	OUT	DIG	LATD<6> data output.
		1	IN	ST	PORTD<6> data input.
	SPP6	1	OUT	DIG	SPP<6> output data; takes priority over port data.
		1	IN	TTL	SPP<6> input data.
	P1C	0	OUT	DIG	ECCP1 Enhanced PWM output, Channel C; takes priority over port and SPP data. ⁽¹⁾
RD7/SPP7/P1D	RD7	0	OUT	DIG	LATD<7> data output.
		1	IN	ST	PORTD<7> data input.
	SPP7	1	OUT	DIG	SPP<7> output data; takes priority over port data.
		1	IN	TTL	SPP<7> input data.
	P1D	0	OUT	DIG	ECCP1 Enhanced PWM output, Channel D; takes priority over port and SPP data. ⁽¹⁾

TABLE 10-7: PORTD I/O SUMMARY

Legend: OUT = Output, IN = Input, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input

Note 1: May be configured for tri-state during Enhanced PWM shutdown events.

TABLE 10-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORT

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
PORTD ⁽³⁾	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	56
LATD ⁽³⁾	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	56
TRISD ⁽³⁾	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	56
PORTE	RDPU ⁽³⁾	—	—	—	RE3 ^(1,2)	RE2 ⁽³⁾	RE1 ⁽³⁾	RE0 ⁽³⁾	56
CCP1CON	P1M1 ⁽³⁾	P1M0 ⁽³⁾	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	55
SPPCON ⁽³⁾		_	_	_	_	—	SPPOWN	SPPEN	57

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTD.

Note 1: Implemented only when Master Clear functionality is disabled (MCLRE Configuration bit = 0).

2: RE3 is the only PORTE bit implemented on both 28-pin and 40/44-pin devices. All other bits are implemented only when PORTE is implemented (i.e., 40/44-pin devices).

3: These registers and/or bits are unimplemented on 28-pin devices.



FIGURE 16-7: EXAMPLE OF FULL-BRIDGE APPLICATION

16.4.5.1 Direction Change in Full-Bridge Mode

In the Full-Bridge Output mode, the P1M1 bit in the CCP1CON register allows the user to control the forward/reverse direction. When the application firmware changes this direction control bit, the module will assume the new direction on the next PWM cycle.

Just before the end of the current PWM period, the modulated outputs (P1B and P1D) are placed in their inactive state, while the unmodulated outputs (P1A and P1C) are switched to drive in the opposite direction. This occurs in a time interval of (4 Tosc * (Timer2 Prescale Value) before the next PWM period begins. The Timer2 prescaler will be either 1, 4 or 16, depending on the value of the T2CKPS1:T2CKPS0 bits (T2CON<1:0>). During the interval from the switch of the unmodulated outputs to the beginning of the next period, the modulated outputs (P1B and P1D) remain inactive. This relationship is shown in Figure 16-8.

Note that in the Full-Bridge Output mode, the ECCP module does not provide any dead-band delay. In general, since only one output is modulated at all times, dead-band delay is not required. However, there is a situation where a dead-band delay might be required. This situation occurs when both of the following conditions are true:

- 1. The direction of the PWM output changes when the duty cycle of the output is at or near 100%.
- 2. The turn-off time of the power switch, including the power device and driver circuit, is greater than the turn-on time.

Figure 16-9 shows an example where the PWM direction changes from forward to reverse at a near 100% duty cycle. At time t1, the outputs, P1A and P1D, become inactive, while output P1C becomes active. In this example, since the turn-off time of the power devices is longer than the turn-on time, a shoot-through current may flow through power devices, QC and QD, (see Figure 16-7) for the duration of 't'. The same phenomenon will occur to power devices, QA and QB, for PWM direction change from reverse to forward.

If changing PWM direction at high duty cycle is required for an application, one of the following requirements must be met:

- 1. Reduce PWM for a PWM period before changing directions.
- 2. Use switch drivers that can drive the switches off faster than they can drive them on.

Other options to prevent shoot-through current may exist.

TABLE 17-4:	ASSIGNMENT OF BUFFER DESCRIPTORS FOR THE DIFFERENT
	BUFFERING MODES

	BDs Assigned to Endpoint										
Endpoint	Mode 0 (No Ping-Pong)		Mode 1 (Ping-Pong on EP0 OUT)		Mod (Ping-Pong	le 2 on all EPs)	Mode 3 (Ping-Pong on all other EPs, except EP0)				
	Out	In	Out	In	Out	In	Out	In			
0	0	1	0 (E), 1 (O)	2	0 (E), 1 (O)	2 (E), 3 (O)	0	1			
1	2	3	3	4	4 (E), 5 (O)	6 (E), 7 (O)	2 (E), 3 (O)	4 (E), 5 (O)			
2	4	5	5	6	8 (E), 9 (O)	10 (E), 11 (O)	6 (E), 7 (O)	8 (E), 9 (O)			
3	6	7	7	8	12 (E), 13 (O)	14 (E), 15 (O)	10 (E), 11 (O)	12 (E), 13 (O)			
4	8	9	9	10	16 (E), 17 (O)	18 (E), 19 (O)	14 (E), 15 (O)	16 (E), 17 (O)			
5	10	11	11	12	20 (E), 21 (O)	22 (E), 23 (O)	18 (E), 19 (O)	20 (E), 21 (O)			
6	12	13	13	14	24 (E), 25 (O)	26 (E), 27 (O)	22 (E), 23 (O)	24 (E), 25 (O)			
7	14	15	15	16	28 (E), 29 (O)	30 (E), 31 (O)	26 (E), 27 (O)	28 (E), 29 (O)			
8	16	17	17	18	32 (E), 33 (O)	34 (E), 35 (O)	30 (E), 31 (O)	32 (E), 33 (O)			
9	18	19	19	20	36 (E), 37 (O)	38 (E), 39 (O)	34 (E), 35 (O)	36 (E), 37 (O)			
10	20	21	21	22	40 (E), 41 (O)	42 (E), 43 (O)	38 (E), 39 (O)	40 (E), 41 (O)			
11	22	23	23	24	44 (E), 45 (O)	46 (E), 47 (O)	42 (E), 43 (O)	44 (E), 45 (O)			
12	24	25	25	26	48 (E), 49 (O)	50 (E), 51 (O)	46 (E), 47 (O)	48 (E), 49 (O)			
13	26	27	27	28	52 (E), 53 (O)	54 (E), 55 (O)	50 (E), 51 (O)	52 (E), 53 (O)			
14	28	29	29	30	56 (E), 57 (O)	58 (E), 59 (O)	54 (E), 55 (O)	56 (E), 57 (O)			
15	30	31	31	32	60 (E), 61 (O)	62 (E), 63 (O)	58 (E), 59 (O)	60 (E), 61 (O)			

Legend: (E) = Even transaction buffer, (O) = Odd transaction buffer

TABLE 17-5:	SUMMARY OF USB BUFFER DESCRIPTOR TABLE REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
BDnSTAT ⁽¹⁾	UOWN	DTS ⁽⁴⁾	PID3 ⁽²⁾ KEN ⁽³⁾	PID2 ⁽²⁾ INCDIS ⁽³⁾	PID1 ⁽²⁾ DTSEN ⁽³⁾	PID0 ⁽²⁾ BSTALL ⁽³⁾	BC9	BC8		
BDnCNT ⁽¹⁾	Byte Count	Byte Count								
BDnADRL ⁽¹⁾	Buffer Address Low									
BDnADRH ⁽¹⁾	Buffer Add	ress High								

Note 1: For buffer descriptor registers, n may have a value of 0 to 63. For the sake of brevity, all 64 registers are shown as one generic prototype. All registers have indeterminate Reset values (xxxx xxxx).

2: Bits 5 through 2 of the BDnSTAT register are used by the SIE to return PID3:PID0 values once the register is turned over to the SIE (UOWN bit is set). Once the registers have been under SIE control, the values written for KEN, INCDIS, DTSEN and BSTALL are no longer valid.

3: Prior to turning the buffer descriptor over to the SIE (UOWN bit is cleared), bits 5 through 2 of the BDnSTAT register are used to configure the KEN, INCDIS, DTSEN and BSTALL settings.

4: This bit is ignored unless DTSEN = 1.

17.10 Overview of USB

This section presents some of the basic USB concepts and useful information necessary to design a USB device. Although much information is provided in this section, there is a plethora of information provided within the USB specifications and class specifications. Thus, the reader is encouraged to refer to the USB specifications for more information (www.usb.org). If you are very familiar with the details of USB, then this section serves as a basic, high-level refresher of USB.

17.10.1 LAYERED FRAMEWORK

USB device functionality is structured into a layered framework graphically shown in Figure 17-13. Each level is associated with a functional level within the device. The highest layer, other than the device, is the configuration. A device may have multiple configurations. For example, a particular device may have multiple power requirements based on Self-Power Only or Bus Power Only modes.

For each configuration, there may be multiple interfaces. Each interface could support a particular mode of that configuration.

Below the interface is the endpoint(s). Data is directly moved at this level. There can be as many as 16 bidirectional endpoints. Endpoint 0 is always a control endpoint and by default, when the device is on the bus, Endpoint 0 must be available to configure the device.

17.10.2 FRAMES

Information communicated on the bus is grouped into 1 ms time slots, referred to as frames. Each frame can contain many transactions to various devices and endpoints. Figure 17-9 shows an example of a transaction within a frame.

17.10.3 TRANSFERS

There are four transfer types defined in the USB specification.

- **Isochronous:** This type provides a transfer method for large amounts of data (up to 1023 bytes) with timely delivery ensured; however, the data integrity is not ensured. This is good for streaming applications where small data loss is not critical, such as audio.
- **Bulk**: This type of transfer method allows for large amounts of data to be transferred with ensured data integrity; however, the delivery timeliness is not ensured.
- Interrupt: This type of transfer provides for ensured timely delivery for small blocks of data, plus data integrity is ensured.
- **Control:** This type provides for device setup control.

While full-speed devices support all transfer types, low-speed devices are limited to interrupt and control transfers only.

17.10.4 POWER

Power is available from the Universal Serial Bus. The USB specification defines the bus power requirements. Devices may either be self-powered or bus powered. Self-powered devices draw power from an external source, while bus powered devices use power supplied from the bus.





19.4.4.5 Clock Synchronization and the CKP bit

When the CKP bit is cleared, the SCL output is forced to '0'. However, clearing the CKP bit will not assert the SCL output low until the SCL output is already sampled low. Therefore, the CKP bit will not assert the SCL line until an external I^2C master device has

already asserted the SCL line. The SCL output will remain low until the CKP bit is set and all other devices on the I^2 C bus have deasserted SCL. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCL (see Figure 19-14).



FIGURE 19-14: CLOCK SYNCHRONIZATION TIMING



19.4.17.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

- a) A low level is sampled on SDA when SCL goes from low level to high level.
- SCL goes low before SDA is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user deasserts SDA and the pin is allowed to float high, the BRG is loaded with SSPADD<6:0> and counts down to '0'. The SCL pin is then deasserted and when sampled high, the SDA pin is sampled.

If SDA is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', see Figure 19-31). If SDA is sampled high, the BRG is reloaded and begins counting. If SDA goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDA at exactly the same time.

If SCL goes from high-to-low before the BRG times out and SDA has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (see Figure 19-32).

If, at the end of the BRG time-out, both SCL and SDA are still high, the SDA pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCL pin, the SCL pin is driven low and the Repeated Start condition is complete.





FIGURE 19-32: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



20.1.3 AUTO-BAUD RATE DETECT

The Enhanced USART module supports the automatic detection and calibration of baud rate. This feature is active only in Asynchronous mode and while the WUE bit is clear.

The automatic baud rate measurement sequence (Figure 20-1) begins whenever a Start bit is received and the ABDEN bit is set. The calculation is self-averaging.

In the Auto-Baud Rate Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. In ABD mode, the internal Baud Rate Generator is used as a counter to time the bit period of the incoming serial byte stream.

Once the ABDEN bit is set, the state machine will clear the BRG and look for a Start bit. The Auto-Baud Rate Detect must receive a byte with the value, 55h (ASCII "U", which is also the LIN bus Sync character), in order to calculate the proper bit rate. The measurement is taken over both a low and a high bit time in order to minimize any effects caused by asymmetry of the incoming signal. After a Start bit, the SPBRG begins counting up, using the preselected clock source on the first rising edge of RX. After eight bits on the RX pin, or the fifth rising edge, an accumulated value totalling the proper BRG period is left in the SPBRGH:SPBRG register pair. Once the 5th edge is seen (this should correspond to the Stop bit), the ABDEN bit is automatically cleared.

If a rollover of the BRG occurs (an overflow from FFFFh to 0000h), the event is trapped by the ABDOVF status bit (BAUDCON<7>). It is set in hardware by BRG rollovers and can be set or cleared by the user in software. ABD mode remains active after rollover events and the ABDEN bit remains set (Figure 20-2).

While calibrating the baud rate period, the BRG registers are clocked at 1/8th the preconfigured clock rate. Note that the BRG clock will be configured by the BRG16 and BRGH bits. Independent of the BRG16 bit setting, both the SPBRG and SPBRGH will be used as a 16-bit counter. This allows the user to verify that no carry occurred for 8-bit modes by checking for 00h in the SPBRGH register. Refer to Table 20-4 for counter clock rates to the BRG.

While the ABD sequence takes place, the EUSART state machine is held in Idle. The RCIF interrupt is set once the fifth rising edge on RX is detected. The value in the RCREG needs to be read to clear the RCIF interrupt. The contents of RCREG should be discarded.

- Note 1: If the WUE bit is set with the ABDEN bit, Auto-Baud Rate Detection will occur on the byte *following* the Break character.
 - 2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible due to bit error rates. Overall system timing and communication baud rates must be taken into consideration when using the Auto-Baud Rate Detection feature.

TABLE 20-4: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Counter Clock
0	0	Fosc/512
0	1	Fosc/128
1	0	Fosc/128
1	1	Fosc/32

Note: During the ABD sequence, SPBRG and SPBRGH are both used as a 16-bit counter, independent of the BRG16 setting.

20.1.3.1 ABD and EUSART Transmission

Since the BRG clock is reversed during ABD acquisition, the EUSART transmitter cannot be used during ABD. This means that whenever the ABDEN bit is set, TXREG cannot be written to. Users should also ensure that ABDEN does not become set during a transmit sequence. Failing to do this may result in unpredictable EUSART operation.



FIGURE 20-2: BRG OVERFLOW SEQUENCE



21.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ACQT2:ACQT0 and ADCS2:ADCS0 bits in ADCON2 should be updated in accordance with the clock source to be used in that mode. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in the Sleep mode requires the A/D FRC clock to be selected. If bits ACQT2:ACQT0 are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

21.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

- Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs will convert as analog inputs. Analog levels on a digitally configured input will be accurately converted.
 - 2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.
 - 3: The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG0 bits in ADCON1 are reset.

22.0 COMPARATOR MODULE

The analog comparator module contains two comparators that can be configured in a variety of ways. The inputs can be selected from the analog inputs multiplexed with pins RA0 through RA5, as well as the on-chip voltage reference (see **Section 23.0 "Comparator Voltage Reference Module**"). The digital outputs (normal or inverted) are available at the pin level and can also be read through the control register. The CMCON register (Register 22-1) selects the comparator input and output configuration. Block diagrams of the various comparator configurations are shown in Figure 22-1.

REGISTER 22-1: CMCON: COMPARATOR CONTROL REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1	R/W-1	
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	
bit 7							bit 0	
Legend:								
R = Readable	bit	W = Writable I	oit	U = Unimpler	mented bit, read	d as '0'		
-n = Value at P	OR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkn	iown	
bit 7	7 C2OUT : Comparator 2 Output bit $\frac{When C2INV = 0:}{1 = C2 VIN+ > C2 VIN-}$ $0 = C2 VIN+ < C2 VIN-$ $\frac{When C2INV = 1:}{1 = C2 VIN+ < C2 VIN-}$ $0 = C2 VIN+ < C2 VIN-$							
bit 6	C1OUT: Comparator 1 Output bit When C1INV = 0: 1 = C1 VIN+ > C1 VIN- 0 = C1 VIN+ < C1 VIN- When C1INV = 1: 1 = C1 VIN+ < C1 VIN- 0 = C1 VIN+ < C1 VIN-							
bit 5	C2INV: Comparator 2 Output Inversion bit 1 = C2 output inverted 0 = C2 output not inverted							
bit 4	C1INV : Comparator 1 Output Inversion bit 1 = C1 output inverted 0 = C1 output not inverted							
bit 3 bit 2-0	3 CIS: Comparator Input Switch bit When CM2:CM0 = 110: 1 = C1 VIN- connects to RA3/AN3/VREF+ C2 VIN- connects to RA2/AN2/VREF-/CVREF 0 = C1 VIN- connects to RA0/AN0 C2 VIN- connects to RA1/AN1 2.0 CM2:CM0: Comparator Mode bits							
	Figure 22-1 st	hows the Comp	arator mode	s and the CM2:	CM0 bit setting	IS.		

25.2 Watchdog Timer (WDT)

For PIC18F2455/2550/4455/4550 devices, the WDT is driven by the INTRC source. When the WDT is enabled, the clock source is also enabled. The nominal WDT period is 4 ms and has the same stability as the INTRC oscillator.

The 4 ms period of the WDT is multiplied by a 16-bit postscaler. Any output of the WDT postscaler is selected by a multiplexer, controlled by bits in Configuration Register 2H. Available periods range from 4 ms to 131.072 seconds (2.18 minutes). The WDT and postscaler are cleared when any of the following events occur: a SLEEP or CLRWDT instruction is executed, the IRCF bits (OSCCON<6:4>) are changed or a clock failure has occurred.

- Note 1: The CLRWDT and SLEEP instructions clear the WDT and postscaler counts when executed.
 - 2: Changing the setting of the IRCF bits (OSCCON<6:4>) clears the WDT and postscaler counts.
 - **3:** When a CLRWDT instruction is executed, the postscaler count will be cleared.

25.2.1 CONTROL REGISTER

Register 25-15 shows the WDTCON register. This is a readable and writable register which contains a control bit that allows software to override the WDT enable Configuration bit, but only if the Configuration bit has disabled the WDT.



FIGURE 25-1: WDT BLOCK DIAGRAM

Mnemonic, Operands			Cycles	, 16-Bit Instruction Word				Status	
		Description		MSb			LSb	Affected	Notes
BIT-ORIENTED OPERATIONS									
BCF	f, b, a	Bit Clear f	1	1001	bbba	ffff	ffff	None	1, 2
BSF	f, b, a	Bit Set f	1	1000	bbba	ffff	ffff	None	1, 2
BTFSC	f, b, a	Bit Test f, Skip if Clear	1 (2 or 3)	1011	bbba	ffff	ffff	None	3, 4
BTFSS	f, b, a	Bit Test f, Skip if Set	1 (2 or 3)	1010	bbba	ffff	ffff	None	3, 4
BTG	f, d, a	Bit Toggle f	1	0111	bbba	ffff	ffff	None	1, 2
CONTROL	OPERA	TIONS							
BC	n	Branch if Carry	1 (2)	1110	0010	nnnn	nnnn	None	
BN	n	Branch if Negative	1 (2)	1110	0110	nnnn	nnnn	None	
BNC	n	Branch if Not Carry	1 (2)	1110	0011	nnnn	nnnn	None	
BNN	n	Branch if Not Negative	1 (2)	1110	0111	nnnn	nnnn	None	
BNOV	n	Branch if Not Overflow	1 (2)	1110	0101	nnnn	nnnn	None	
BNZ	n	Branch if Not Zero	1 (2)	1110	0001	nnnn	nnnn	None	
BOV	n	Branch if Overflow	1 (2)	1110	0100	nnnn	nnnn	None	
BRA	n	Branch Unconditionally	2	1101	0nnn	nnnn	nnnn	None	
BZ	n	Branch if Zero	1 (2)	1110	0000	nnnn	nnnn	None	
CALL	n, s	Call Subroutine 1st word	2	1110	110s	kkkk	kkkk	None	
		2nd word		1111	kkkk	kkkk	kkkk		
CLRWDT	—	Clear Watchdog Timer	1	0000	0000	0000	0100	TO, PD	
DAW	—	Decimal Adjust WREG	1	0000	0000	0000	0111	С	
GOTO	n	Go to Address 1st word	2	1110	1111	kkkk	kkkk	None	
		2nd word		1111	kkkk	kkkk	kkkk		
NOP	—	No Operation	1	0000	0000	0000	0000	None	
NOP	—	No Operation	1	1111	XXXX	XXXX	XXXX	None	4
POP	—	Pop Top of Return Stack (TOS)	1	0000	0000	0000	0110	None	
PUSH	—	Push Top of Return Stack (TOS)	1	0000	0000	0000	0101	None	
RCALL	n	Relative Call	2	1101	lnnn	nnnn	nnnn	None	
RESET		Software Device Reset	1	0000	0000	1111	1111	All	
RETFIE	S	Return from Interrupt Enable	2	0000	0000	0001	000s	GIE/GIEH,	
DETUN								PEIE/GIEL	
REILW	K	Return with Literal in WREG	2	0000	1100	kkkk	kkkk	None	
RETURN	S	Return from Subroutine	2	0000	0000	0001	001s	None	
SLEEP	_	Go into Standby mode	1	0000	0000	0000	0011	10, PD	

TABLE 26-2: PIC18FXXXX INSTRUCTION SET (CONTINUED)

Note 1: When a PORT register is modified as a function of itself (e.g., MOVF PORTB, 1, 0), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as an input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If the Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

4: Some instructions are two-word instructions. The second word of these instructions will be executed as a NOP unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

SUBWFB	Sı	ubtract V	V from f w	ith B	orrow				
Syntax:	Sl	SUBWFB f {,d {,a}}							
Operands:		$0 \le f \le 255$							
		d ∈ [0,1]							
		a ∈ [0,1]							
Operation:	(f)	$(f) - (W) - (\overline{C}) \rightarrow dest$							
Status Affected:	N,	N, OV, C, DC, Z							
Encoding:		0101	10da	fff	f ffff				
Description:		Subtract W and the Carry flag (borrow) from register 'f' (2's complement method). If 'd' is '0', the result is stored back in register 'f' (default). If 'a' is '0', the Access Bank is selected. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default). If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed							
Words [.]	1		set mode						
Cycles:	1								
Q Cycle Activity	·								
Q1		Q2	Q3		Q4				
Decode		Read	Proces	s	Write to				
	reę	gister 'f'	Data		destination				
Example 1:	S	SUBWFB	REG, 1,	0					
Before Instruc	ction	10h	(0001	100	111				
W KEG	=	0Dh	(0000)	1100)1)				
С	=	1							
After Instruction	on =	0Ch	(0000	1011)					
W	=	0Dh	(0000	110	1)				
Z	=	0							
Ν	=	0	; result	is po	ositive				
Example 2:	S	SUBWFB	REG, 0,	0					
Before Instruc	ction	106	(0001	1 0 1	1.				
REG W	=	1Ah	(0001	101	.1)				
С	=	0	,						
After Instruction	on =	1Bh	(0001	101	1)				
W	=	00h	(0001	TOT	1011)				
C Z	=	1	: result is zero						
Ň	=	ò	, 100011	10 20					
Example 3:	5	SUBWFB	REG, 1,	0					
Before Instruc	ction	0.01-							
REG W	=	= 03h = 0Eh	(0000 0011) (0000 1101)						
Ĉ	=	1	(_,				
After Instruction	on =	F5h	(1111	010	0)				
NLO	-	1 011	; [2's co	omp]	,				
W C	=	0Eh 0	(0000	110	1)				
Ž	=	Õ							
N	=	1	; result	is ne	gative				

SWAPF	Swap f						
Syntax:	SWAPF f	SWAPF f {,d {,a}}					
Operands:	$0 \le f \le 255$ $d \in [0,1]$ $a \in [0,1]$	$\begin{array}{l} 0 \leq f \leq 255 \\ d \in [0,1] \\ a \in [0,1] \end{array}$					
Operation:	(f<3:0>) → (f<7:4>) →	(f<3:0>) → dest<7:4>, (f<7:4>) → dest<3:0>					
Status Affected:	None	None					
Encoding:	0011	10da	ffff	ff ffff			
Description:	The upper a 'f' are excha- is placed in re If 'a' is '0', t If 'a' is '1', t GPR bank If 'a' is '0' a set is enabl in Indexed mode wher Section 26 Bit-Oriente Literal Offe	The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in register 'f' (default). If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default). If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See Section 26.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode" for dotails					
Words:	1						
Cycles:	1	1					
Q Cycle Activity:							
Q1	Q2	Q3		Q4			
Decode	Read	Proce	ess Write to				
	register 'f'	Data	a de	stination			
Example: SWAPF REG, 1, 0 Before Instruction REG = 53h After Instruction							
REG	REG = 3511						





TABLE 28-6: HIGH/LOW-VOLTAGE DETECT CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial								
Param No.	Symbol	Characteristic		Min	Тур	Max	Units	Conditions
D420		HLVD Voltage on VDD	HLVDL<3:0> = 0000	2.06	2.17	2.28	V	
		Transition High-to-Low	HLVDL<3:0> = 0001	2.12	2.23	2.34	V	
			HLVDL<3:0> = 0010	2.24	2.36	2.48	V	
			HLVDL<3:0> = 0011	2.32	2.44	2.56	V	
			HLVDL<3:0> = 0100	2.47	2.60	2.73	V	
			HLVDL<3:0> = 0101	2.65	2.79	2.93	V	
			HLVDL<3:0> = 0110	2.74	2.89	3.04	V	
			HLVDL<3:0> = 0111	2.96	3.12	3.28	V	
			HLVDL<3:0> = 1000	3.22	3.39	3.56	V	
			HLVDL<3:0> = 1001	3.37	3.55	3.73	V	
			HLVDL<3:0> = 1010	3.52	3.71	3.90	V	
			HLVDL<3:0> = 1011	3.70	3.90	4.10	V	
			HLVDL<3:0> = 1100	3.90	4.11	4.32	V	
			HLVDL<3:0> = 1101	4.11	4.33	4.55	V	
			HLVDL<3:0> = 1110	4.36	4.59	4.82	V	
			HLVDL<3:0> = 1111	1.14	1.20	1.26	V	Voltage at HLVDIN input pin compared to Internal Voltage Reference

29.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Graphs and tables are not available at this time.

28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









	Units			MILLIMETERS				
	MIN	NOM	MAX					
Number of Pins	N							
Pitch	e	1.27 BSC						
Overall Height	A	-	2.65					
Molded Package Thickness	A2	2.05	-	-				
Standoff §	A1	0.10	-	0.30				
Overall Width	E	10.30 BSC						
Molded Package Width	E1	7.50 BSC						
Overall Length	D	17.90 BSC						
Chamfer (optional)	h	0.25 –		0.75				
Foot Length	L	0.40	-	1.27				
Footprint	L1	1.40 REF						
Foot Angle Top	ф	0°	-	8°				
Lead Thickness	С	0.18	-	0.33				
Lead Width	b	0.31	-	0.51				
Mold Draft Angle Top	α	5°	-	15°				
Mold Draft Angle Bottom	β	5°	_	15°				

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic.

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.

4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B